

| L Number | Hits | Search Text | DB | Time stamp |
|----------|-------|---|----------------------------------|------------------|
| 1 | 95116 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) | USPAT; US-PGPUB | 2003/10/03 20:27 |
| 2 | 41998 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3 | USPAT; US-PGPUB | 2003/10/03 20:27 |
| 3 | 29778 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric) | USPAT; US-PGPUB | 2003/10/03 20:28 |
| 4 | 19779 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric) and etch\$3 | USPAT; US-PGPUB | 2003/10/03 20:03 |
| 5 | 17404 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric) and etch\$3) and (trench recess open\$3 hole groove) | USPAT; US-PGPUB | 2003/10/03 20:28 |
| 6 | 16468 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric) and etch\$3) and (trench recess open\$3 hole groove) and (semiconductor wafer substrate) | USPAT; US-PGPUB | 2003/10/03 20:04 |
| 7 | 16445 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric) and etch\$3) and (trench recess open\$3 hole groove) and (semiconductor wafer substrate) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel))) | USPAT; US-PGPUB | 2003/10/03 20:14 |
| 8 | 11101 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric) and etch\$3) and (trench recess open\$3 hole groove) and (semiconductor wafer substrate) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel))) and (PR photoresist resist photo?resist) | USPAT; US-PGPUB | 2003/10/03 20:07 |
| 9 | 5001 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric) and etch\$3) and (trench recess open\$3 hole groove) and (semiconductor wafer substrate) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel))) and (PR photoresist resist photo?resist) and resin | USPAT; US-PGPUB | 2003/10/03 20:28 |
| 10 | 147 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric) and etch\$3) and (trench recess open\$3 hole groove) and (semiconductor wafer substrate) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel))) and (PR photoresist resist photo?resist) and resin) and ((electroless near3 plat\$3) electro?plat\$3 (electro near3 plat\$3)) | USPAT; US-PGPUB | 2003/10/03 20:14 |
| 11 | 13409 | conduct\$3 near5 foil | USPAT; US-PGPUB | 2003/10/03 20:13 |
| 12 | 10122 | (conduct\$3 near5 foil) and (trench recess open\$3 hole groove) | USPAT; US-PGPUB | 2003/10/03 20:14 |
| 13 | 9566 | ((conduct\$3 near5 foil) and (trench recess open\$3 hole groove)) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel))) | USPAT; US-PGPUB | 2003/10/03 20:14 |
| 14 | 142 | ((conduct\$3 near5 foil) and (trench recess open\$3 hole groove)) and (copper Cu aluminum Al (iron?nickel (iron near3 nickel))) and ((electroless near3 plat\$3) electro?plat\$3 (electro near3 plat\$3)) | USPAT; US-PGPUB | 2003/10/03 20:15 |
| 15 | 6911 | conductive near3 foil | USPAT; US-PGPUB | 2003/10/03 20:16 |
| 16 | 31 | (conductive near3 foil) and (isolat\$3 near5 trench) | USPAT; US-PGPUB | 2003/10/03 20:16 |
| 17 | 65334 | (conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet)) | EPO; JPO; DERWENT; IBM_TDB | 2003/10/03 20:27 |

| | | | | |
|----|------|--|----------------------------------|------------------|
| 18 | 8676 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3 | EPO; JPO; DERWENT; IBM_TDB | 2003/10/03 20:28 |
| 19 | 3516 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric) | EPO; JPO; DERWENT; IBM_TDB | 2003/10/03 20:28 |
| 20 | 1446 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric) and (trench recess open\$3 hole groove) | EPO; JPO; DERWENT; IBM_TDB | 2003/10/03 20:28 |
| 21 | 271 | ((conduct\$3 near5 foil) or ((copper aluminum) near5 (film sheet))) and pattern\$3) and (insulat\$3 dielectric) and (trench recess open\$3 hole groove) and resin | EPO; JPO; DERWENT; IBM_TDB | 2003/10/03 20:29 |